

PCT

WORLD INTELLECTUAL PROPERTY ORGANIZATION
International Bureau



9902586-8
1003
copy

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : C08L 73/00, H01L 23/31, 23/498		A1	(11) International Publication Number: WO 98/27161
			(43) International Publication Date: 25 June 1998 (25.06.98)
(21) International Application Number: PCT/EP97/07157		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, GW, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG).	
(22) International Filing Date: 15 December 1997 (15.12.97)		Published <i>With international search report.</i> <i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>	
(30) Priority Data: 08/768,056 16 December 1996 (16.12.96) US			
(71) Applicant: SHELL INTERNATIONALE RESEARCH MAATSCHAPPIJ B.V. [NL/NL]; Carel van Bylandtlaan 30, NL-2596 HR The Hague (NL).			
(72) Inventors: IYER, Shridhar, Ratnaswamy; 16930 Ascot Meadow Drive, Sugar Land, TX 77479 (US). WONG, Pui, Kwan; 6431 Mercer Street, Houston, TX 77005 (US).			
(54) Title: THERMOSETTING ENCAPSULANTS FOR ELECTRONICS PACKAGING			
(57) Abstract An electronic package is provided wherein a semiconductor device on a substrate is encapsulated with a thermally reworkable encapsulant composition comprising: (a) a thermally reworkable cross-linked resin produced by reacting at least one dienophile having a functionality greater than one and at least one 2,5-dialkyl substituted furan-containing polymer, and (b) at least one filler present from 25 to 75 percent by weight based upon the amount of components (a) and (b). Such a process provides a readily reworkable electronic package.			